

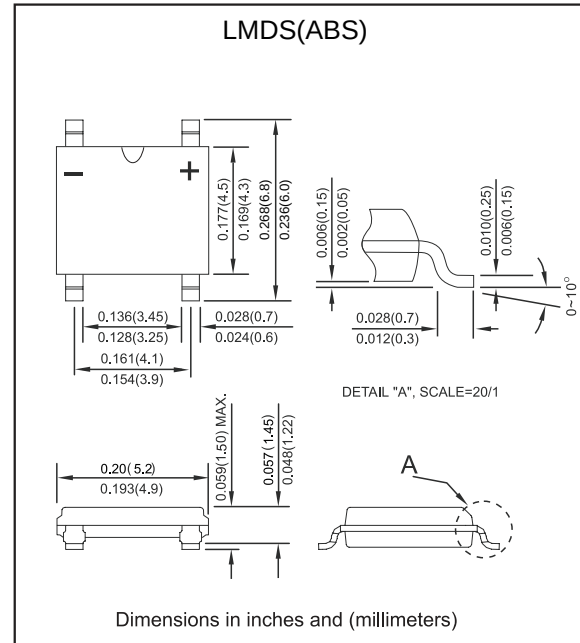
Features

- Surge overload ratings to 50 amperes peak.
- 2.0A rating in low profile surface mount mini-dip bridge save space on printed circuit board.
- Ideal for automated replacement.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Silicon eplana epitaxial chip, metal silicon junction.
- Lead-free parts meet RoHS requirments.
- Compliant to Halogen-free

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, LMDS(ABS)
- Terminals : Solder plated, solderable per MIL-STD-202, Method 208
- Polarity : marked on body
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Average Forward rectified current	See Fig.1	I_{AV}			2.0	A
Peak Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} \quad T_J = 25^{\circ}\text{C}$	I_R			0.1	mA
	$V_R = V_{RRM} \quad T_J = 100^{\circ}\text{C}$				10	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		50		$^{\circ}\text{C/W}$
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		20		pF
Storage temperature		T_{STG}	-55		+150	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature T_J , (°C)
KABS22	20	14	20	0.55	-55 to +150
KABS24	40	28	40		
KABS26	60	42	60	0.70	
KABS28	80	56	80	0.85	
KABS210	100	70	100		
KABS215	150	105	150	0.90	
KABS220	200	140	200		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage
per element at 2.0A peak

Rating and characteristic curves

Fig. 1 Output Current Derating Curve

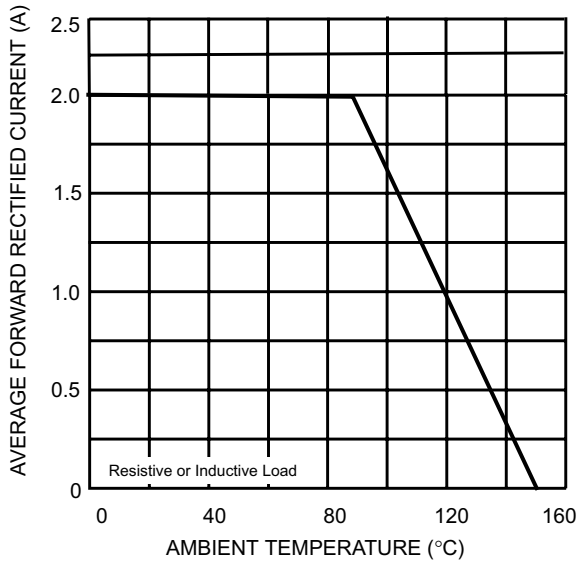


Fig. 2 Typical Forward Characteristics (per leg)

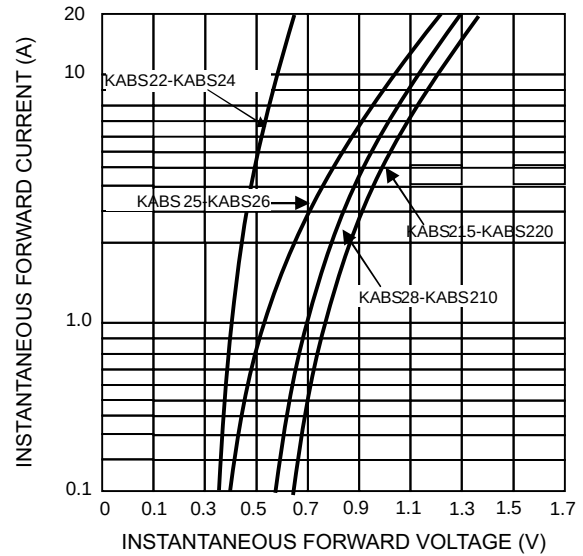


Fig. 3 Maximum Peak Forward Surge Current (per leg)

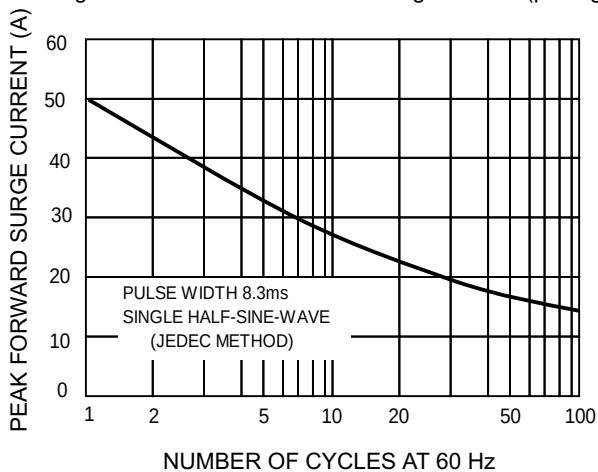


Fig. 5 Typical Junction Capacitance

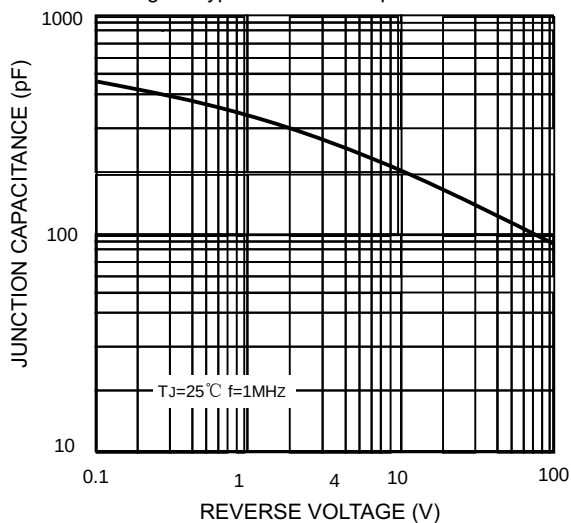
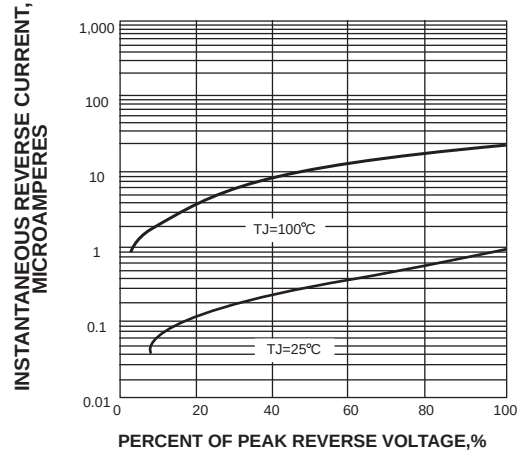
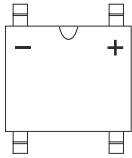
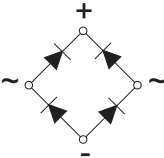


FIG. 4-TYPICAL REVERSE CHARACTERISTICS



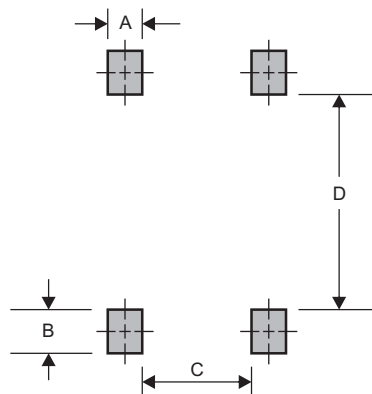
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code	Example
KABS22	KABS22	 LOGO Marking code
KABS24	KABS24	
KABS26	KABS26	
KABS28	KABS28	
KABS210	KABS210	
KABS215	KABS215	
KABS220	KABS220	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LMDS/ABS	0.024 (0.60)	0.024 (0.60)	0.132 (3.35)	0.193 (4.90)